

LUXBEAM® LLS05

Advanced packaging at 5 μm

A 405 / 375 nm laser photohead for AP redistribution and interposers, IC substrate, glass build-up and mSAP fineline — on panels from 310 × 310 up to 600 × 600 mm.

Full specification

IMAGING & LAYOUT	
Resolution	5 μm
Light source	405 / 375 nm laser
Typical applications	AP RDL / interposers, IC substrate, glass build-up, mSAP fine-line
Substrate / panel	310×310, 510×515, 600×600
Segment	Advanced packaging

Figures are for discussion and to be confirmed per application. Throughput depends on resist and energy density — send us both and a field application engineer will verify them for your process.

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Specifications are subject to change. The official product datasheet remains the authoritative reference.